Lattice Semiconductor Corporation - <u>LFEC10E-4F484I Datasheet</u>



Welcome to **E-XFL.COM**

Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	10200
Total RAM Bits	282624
Number of I/O	288
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec10e-4f484i

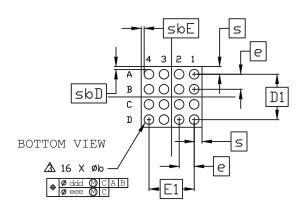
Email: info@E-XFL.COM

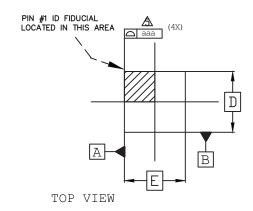
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

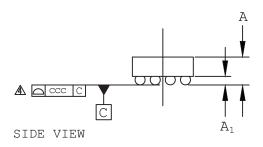


16-Ball WLCS Package Option 2: iCE40 UltraLite™

Dimensions in Millimeters







- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- \triangle PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- $\underline{\mathbb{A}}$ BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

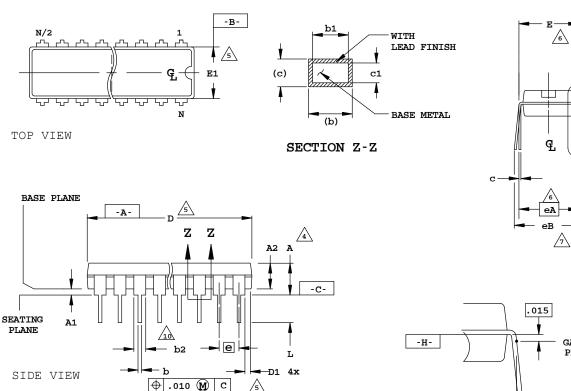
REF.	Min.	Nom.	Max.	
Α	0.413	0.452	0.491	
A1	0.122	0.152	0.182	
b	0.188	0.218	0.248	
D	1.	409 BS	С	
Ε	1.	409 BS	С	
D1		1.05 BSC)	
E1	1.05 BSC			
е	(0.35 BS0)	
S	-	0.180	-	
sbD	0.067	0.071	0.072	
sbE	0.067	0.071	0.072	
ممم	0.03			
CCC	0.03			
ddd	0.050			
eee		0.015		

SEE DETAIL



20-Pin Plastic DIP Package

Dimensions in Inches



- 1. CONTROLLING DIMENSION: INCH.
- 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M
- 3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR
- PROTRUSIONS TO BE .005 MINIMUM. DIMENSIONS A, A1 & L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING
- PLANE GAUGE GS-3.
- PLANE GAGE GS-3.

 DIMENSIONS D, D1 AND E1
 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

 MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010

 6 E AND eA MEASURED WITH THE LEADS CONSTRAINED

 TO BE PERPENDICULAR TO DATUM C-
- 70 BE PERPENDICULAR TO DATOM.

 eB AND eC ARE MEASURED AT THE LEAD TIPS

 MITH THE LEADS UNCONSTRAINED. 8 N IS THE MAXIMUM NUMBER OF LEAD
- POSITIONS.

 9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
- 10 b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
- 11 DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD , WHERE LEAD EXITS BODY

-Н-	GAGE
	—— ec

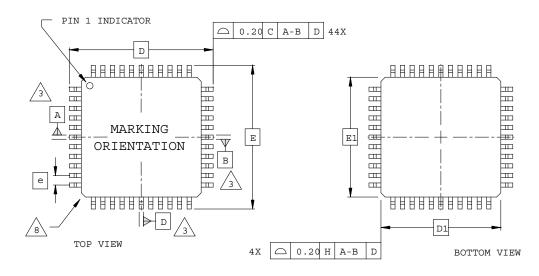
DETAIL A

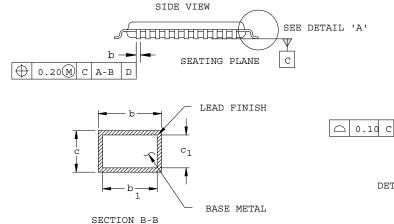
]			
S Y M B	I	NCHES		N O T
O L	MIN.	NOM.	MAX.	T E
Α	-	ı	.210	4
A 1	.015	-	-	4
A 2	.115	.130	.195	
b	.014	.018	.022	
b1	.014	.018	.020	
b2	.045	.060	.070	10
С	.008	.010	.014	
C1	.008	.010	.011	
D	.980	1.030	1.060	5
D1	.005	1	-	5
E	.300	.310	. 325	6
E1	.240	.250	.280	5
е				
еA	.300 BSC			6
eВ	-	-	.430	7
eC	.000	-	.060	7
L	.115	.130	.150	4

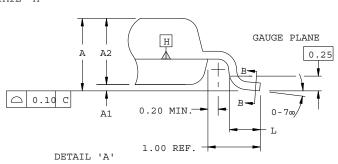


44-Pin TQFP Package (1.0 mm thick)

Dimensions in Millimeters







NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\stackrel{\textstyle \wedge}{}_3$ datums a, b and d to be determined at datum plane H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

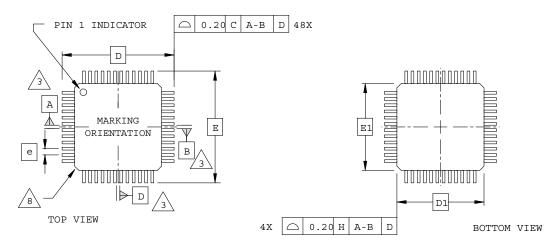
8 EXACT SHAPE OF EACH CORNER IS OPTIONAL.

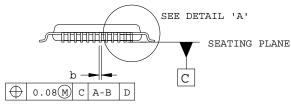
SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.05	-	0.15
A2	. 95	1.00	1.05
D		12.00 BSC	
D1		10.00 BSC	
E	12.00 BSC		
E1	10.00 BSC		
L	0.45	0.75	
N	44		
е		0.80 BSC	
b	0.30 0.37 0.4		
b1	0.30	0.35	0.40
С	0.09	0.15	0.20
c1	0.09	0.13	0.16

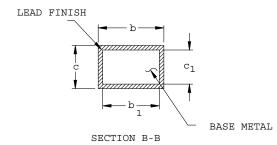


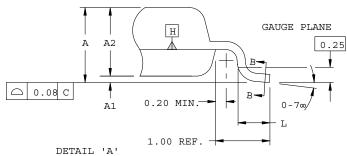
48-Pin TQFP Package (1.0 mm thick)

Dimensions in Millimeters









NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\stackrel{\textstyle }{\searrow}$ datums a, b and d to be determined at datum plane H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

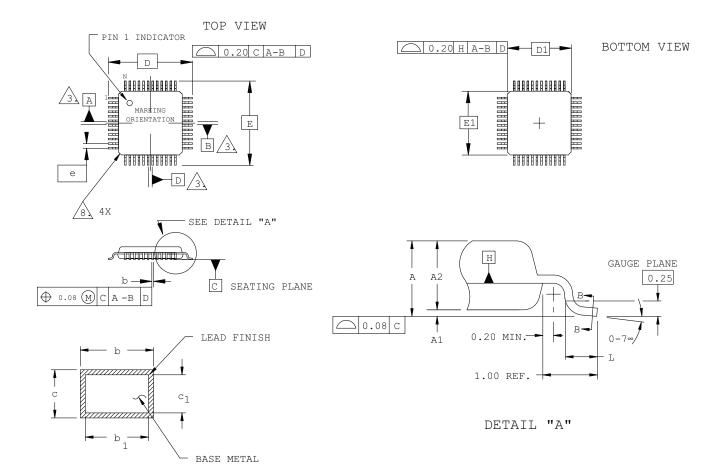
8 EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.	
A	-	-	1.20	
A1	0.05	-	0.15	
A2	. 95	1.00	1.05	
D		9.00 BSC		
D1		7.00 BSC		
E	9.00 BSC			
E1	7.00 BSC			
L	0.45 0.60 0.75			
N	48			
е		0.50 BSC		
b	0.17 0.22 0.27			
b1	0.17 0.20 0		0.23	
С	0.09	0.15	0.20	
c1	0.09	0.13	0.16	



48-Pin TQFP Package (1.4 mm thick)

Dimensions in Millimeters



SECTION B - B

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- $\sqrt{3}$ DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
 ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

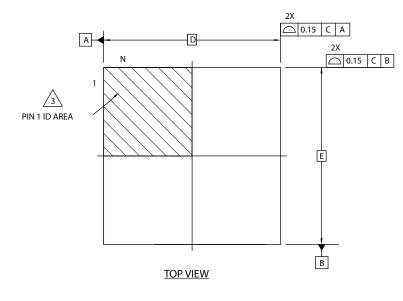
Λ							
/8\	EXACT	SHAPE	OF	EACH	CORNER	IS	OPTIONAL.
\sim							

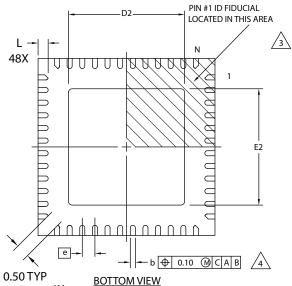
SYMBOL	MIN.	NOM.	MAX.	
A	-	-	1.60	
A1	0.05	-	0.15	
A2	1.35	1.40	1.45	
D		9.00 BSC		
D1		7.00 BSC		
E	9.00 BSC			
E1	7.00 BSC			
L	0.45	0.75		
N	48			
е		0.50 BSC		
b	0.17 0.22 0.27			
b1	0.17	0.20	0.23	
С	0.09	0.15	0.20	
c1	0.09	0.13	0.16	

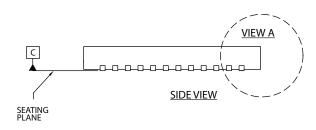


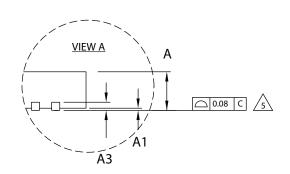
48-Pin QFN Package Option 1

Dimensions in Millimeters









NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\underline{ \begin{tabular}{ll} λ & EXACT SHAPE AND SIZE OF THIS \\ FEATURE IS OPTIONAL. \end{tabular}$

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

APPLIES TO EXPOSED PORTION OF TERMINALS.

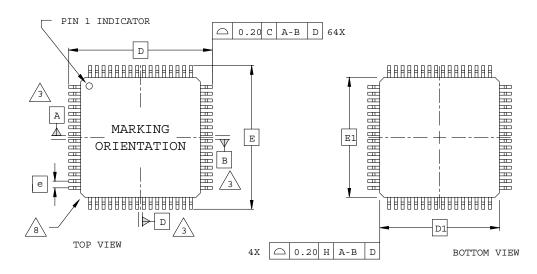
SYMBOL	MIN.	NOM.	MAX.
А	0.80	0.90	1.00
A1	0.00	0.02	0.05
А3	0.2 REF		
D	7.0 BSC		
D2	3.00	-	5.80
E	7.0 BSC		
E2	3.00	-	5.80
b	0.18	0.24	0.30
е	0.50 BSC		
L	0.30	0.40	0.50

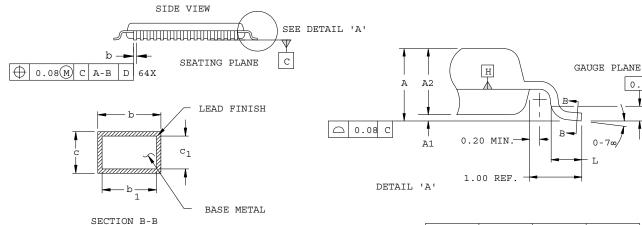
0.25



64-Pin TQFP Package

Dimensions in Millimeters





NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- ALL DIMENSIONS ARE IN MILLIMETERS.

DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

/8\ EXACT SHAPE OF EACH CORNER IS OPTIONAL.

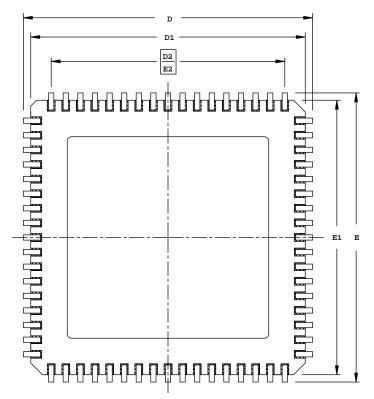
SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D		12.00 BSC	
D1		10.00 BSC	
E		12.00 BSC	
E1	10.00 BSC		
L	0.45	0.75	
N	64		
е		0.50 BSC	
b	0.17 0.22 0.27		
b1	0.17 0.20		0.23
С	0.09	-	0.20
c1	0.09	-	0.16

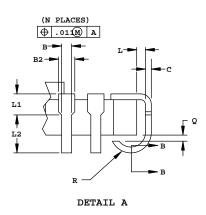


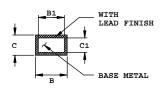
68-Pin JLCC Package

Dimensions in Inches

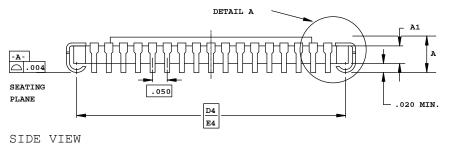
BOTTOM VIEW







SECTION B-B



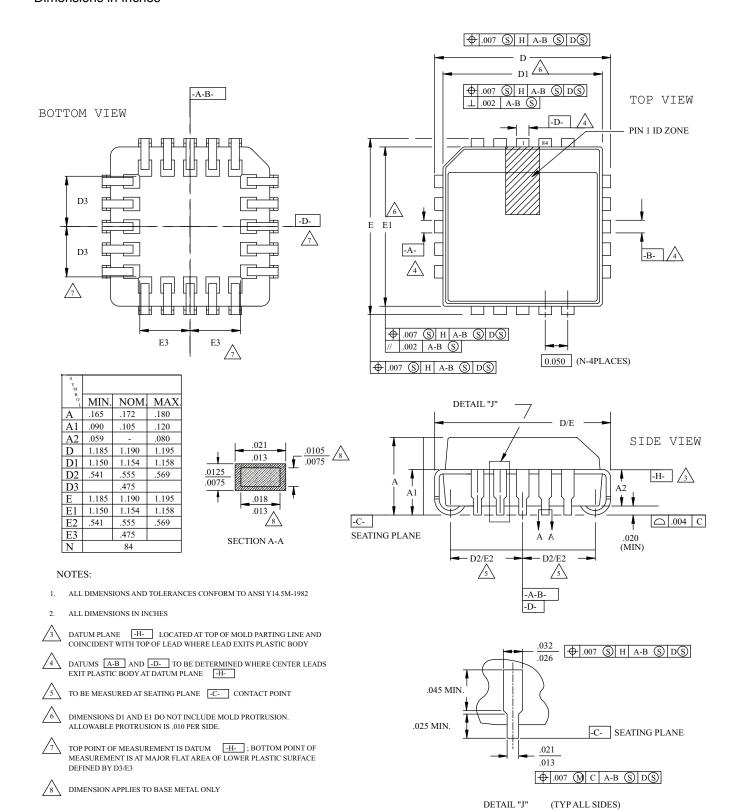
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.
- 3. CORNER CHAMFERS AND/OR NOTCHES ARE OPTIONAL.

S M B O L	INCHES					
o r	MIN.	MIN. M				
A	.115	ı	.190			
A1	. (80 RE	F			
В	.013	-	.023			
B1	.013	-	.020			
B2	.022	-	.035			
С	.007	-	.013			
C1	.007	-	.010			
D/E	.975	.990	1.000			
D1/E1	.920	1	.960			
D2/E2	. 8	00 BS	С			
D4/E4	. 9	30 BS	C			
L	.005	-	ı			
L1	.020	-	-			
L2	.025	-	-			
Q	.003	1	-			
R	.020	•	.040			
N	68					



84-Pin PLCC Package

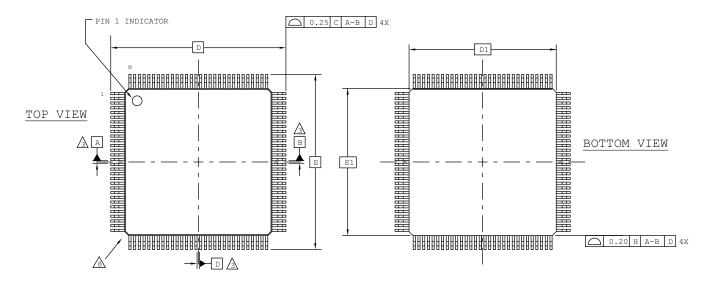
Dimensions in Inches

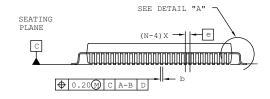


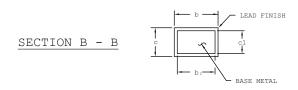


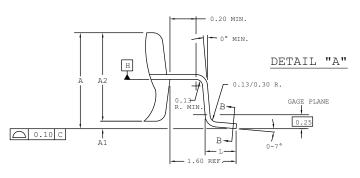
120-Pin PQFP Package

Dimensions in Millimeters









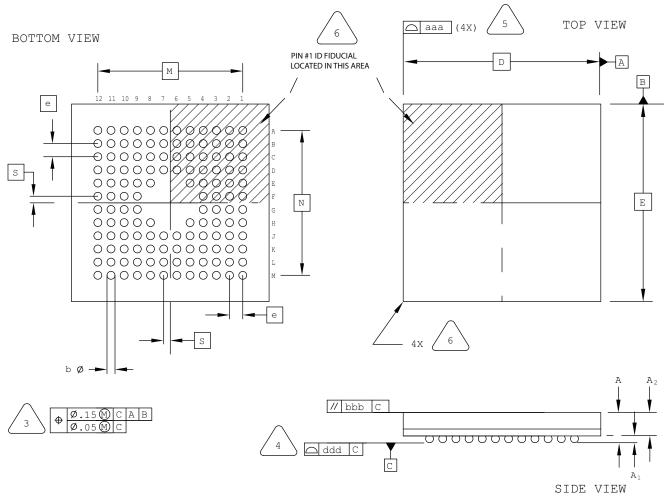
- 1.0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2.0 ALL DIMENSIONS ARE IN MILLIMETERS.
- A DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 4.0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5.0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 7.0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- $\stackrel{\textstyle \wedge}{\underline{\mathop{\otimes}}}$ exact shape of each corner is optional.
- SEXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.	
A	-	-	4.10	
A1	0.25	-	0.50	
A2	3.20	3.40	3.60	
D		31.20 BSC	!	
D1		28.00 BSC		
E	31.20 BSC			
E1	28.00 BSC			
L	0.73 0.88		1.03	
N	120			
е	0.80 BSC			
b	0.29 -		0.45	
b1	0.29 0.35		0.41	
С	0.11	-	0.23	
c1	0.11	0.15	0.19	



132-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

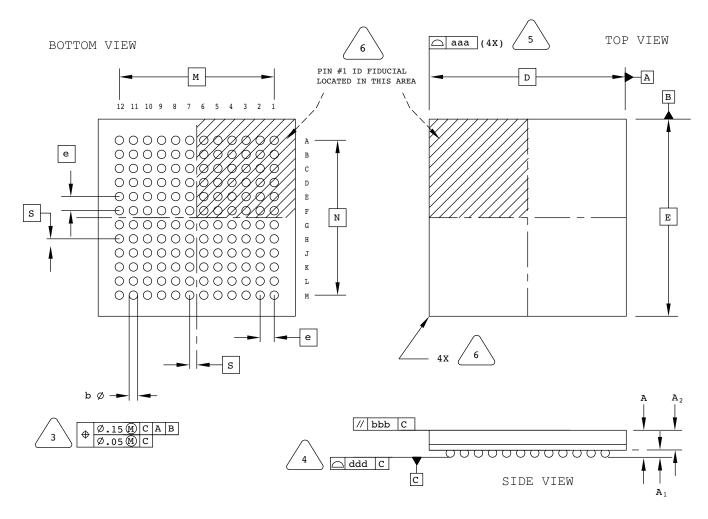


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.10	-	ı
A2	-	_	0.90
D/E	6	.00 BSC	
M/N	4.40 BSC		
S	0.20 BSC		
b	0.20	0.25	0.30
е	0.40 BSC		
aaa			0.10
bbb	_	-	0.10
ddd	_	_	0.08



144-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

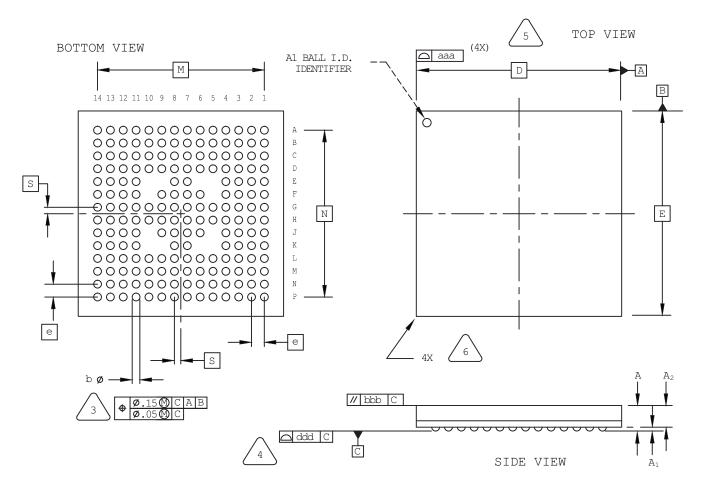


SYMBOL	MIN.	NOM.	MAX.
А	0.90	1.00	1.10
A1	0.15	-	ı
A2	-	-	0.85
D/E	7	.00 BSC	
M/N	5.50 BSC		
s	0.25 BSC		
b	0.25	0.30	0.35
е	0.50 BSC		
aaa			0.10
bbb	-	-	0.10
ddd	-	-	0.08



184-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

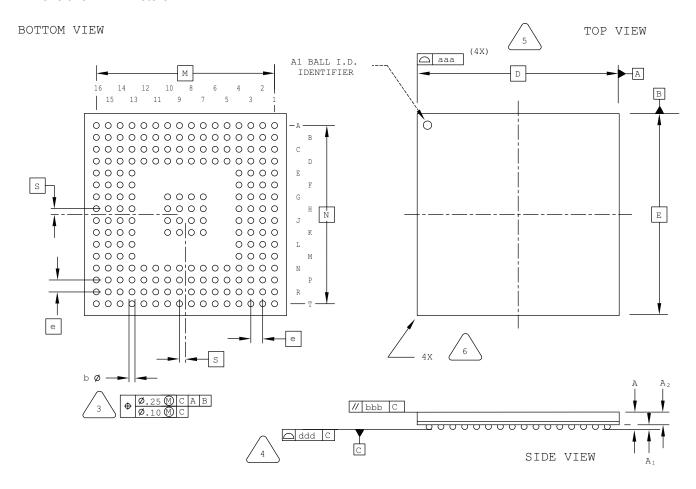


SYMBOL	MIN.	NOM.	MAX.
А	1.20	1.35	1.50
A1	0.16	_	-
A2	_	_	1.34
D/E	8	.00 BSC	
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
е	0.50 BSC		
aaa	0.10		
bbb	_	_	0.10
ddd	_	_	0.08



208-Ball ftBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

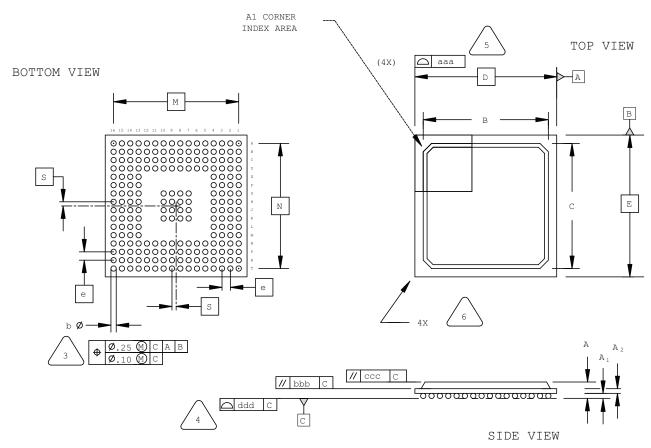


SYMBOL	MIN.	NOM.	MAX.
А	1.25	1.40	1.55
A1	0.30	_	-
A2	_	_	1.25
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
е	1.0 BSC		
aaa	_	_	0.20
bbb	_	_	0.25
ddd	_	_	0.12



208-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

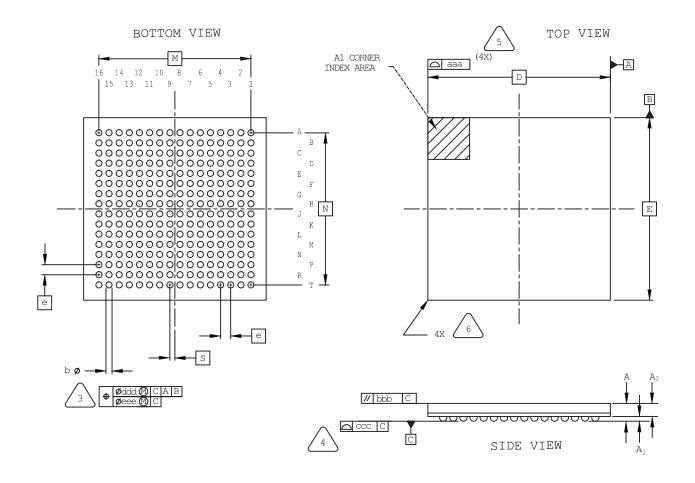


SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	14.80	15.30	15.80
D/E	1	7.00 BSC	
M/N	15.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1	.00 BSC	
aaa	_	_	0.20
bbb	_	_	0.25
ccc	_	_	0.35
ddd	_	_	0.20



256-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\boxed{\mathbb{C}}$.



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

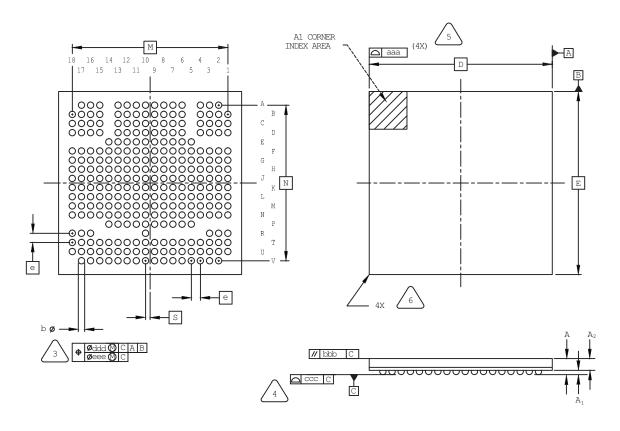


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.15	0.24	_
A2	ı	0.66	-
D/E		9.00 BSC	
M/N		7.50 BSC	
S	0.25 BSC		
b	0.25 0.30 0.35		
е	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		
		·	



285-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

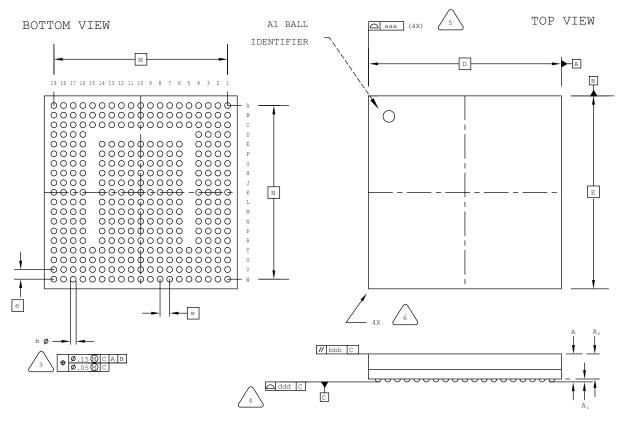


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.30
A1	0.15	_	_
A2	-	-	1.00
D/E	1	0.00 BSC	
M/N	8.50 BSC		
S	0.25 BSC		
b	0.25 0.30		0.35
е	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		



328-Ball csBGA Package

Dimensions in Millimeters



SIDE VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

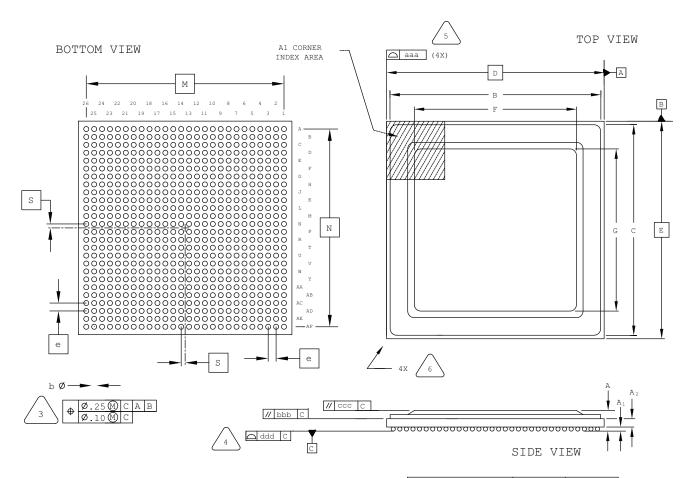


SYMBOL	MIN.	NOM.	MAX.
А	1.05	1.35	1.50
A1	0.15	_	_
A2	_	_	1.20
D/E	10.0 BSC		
M/N	9.00 BSC		
b	0.25	0.30	0.35
е	0.50 BSC		
aaa	_	-	0.10
bbb	-	-	0.10
ddd	_	_	0.08



676-Ball fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

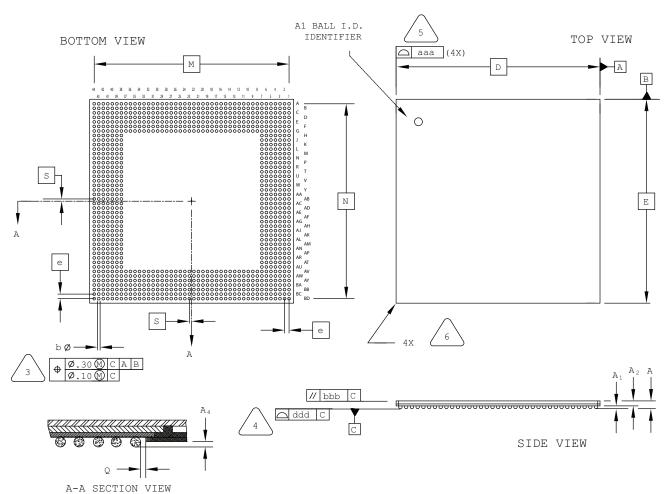


SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.40	0.50	0.60
A2	1	1.20 REF	
B/C	26.55	26.60	26.65
D/E	2	7.00 BSC	
F/G	18.55	18.60	18.65
M/N	25.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	_	_	0.20



1036-Ball ftSBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.80
A1	0.40	0.55	0.70
A2	0.90	0.98	1.10
D/E	4.	5.00 BSC	
M/N	43.00 BSC		
S	0.50 BSC		
b	0.50	0.65	0.80
е	1.00 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.35
ddd	-	-	0.20